

Taiwan Semiconductor

# 2A, 200V - 1000V Standard Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placeme
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Switching mode converters and inverters
- General purpose

#### **MECHANICAL DATA**

Case: SOD-128

• Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

• Meet JESD 201 class 2 whisker test

Polarity: Indicated by cathode band

• Weight: 0.027g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	2	Α	
V <sub>RRM</sub>	200 - 1000	V	
I <sub>FSM</sub>	50	Α	
T <sub>J MAX</sub>	150	°C	
Package	SOD-128		
Configuration	Single die		







**SOD-128** 



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	S2DFS	S2GFS	S2JFS	S2KFS	S2MFS	UNIT
Marking code on the device			S2DFS	S2GFS	S2JFS	S2KFS	S2MFS	
Repetitive peak reverse voltage		$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	140	280	420	560	700	V
Forward current		I <sub>F</sub>	2					Α
Surge peak forward current, single half sine-wave superimposed on rated load $t = 8.3 \text{ms}$ t = 1.0 ms			50					Α
		I <sub>FSM</sub>			140			Α
Junction temperature		$T_J$	-55 to +150					°C
Storage temperature		T <sub>STG</sub>	-55 to +150				°C	

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	14	°C/W	
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	74	°C/W	
Junction-to-case thermal resistance	R <sub>eJC</sub>	20	°C/W	

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
	$I_F = 1A, T_J = 25^{\circ}C$		0.91	-	V
Forward voltage <sup>(1)</sup>	$I_F = 2A, T_J = 25^{\circ}C$	$V_{F}$	0.98	1.10	V
	I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C		0.79	-	V
	$I_F = 2A, T_J = 125$ °C		0.88	0.98	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C		-	1	μΑ
neverse current @ rated v <sub>R</sub>	T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	33	μΑ
Junction capacitance	1MHz, V <sub>R</sub> = 4.0V	C <sub>J</sub>	12	-	pF

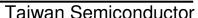
#### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING		
S2xFS	SOD-128	14,000 / Tape & Reel		

#### Notes:

1. "x" defines voltage from 200V(S2DFS) to 1000V(S2MFS)





#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve

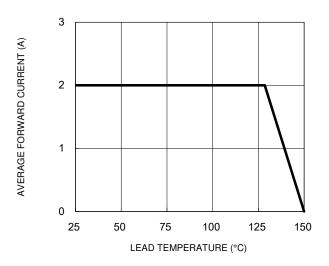


Fig.3 Typical Reverse Characteristics

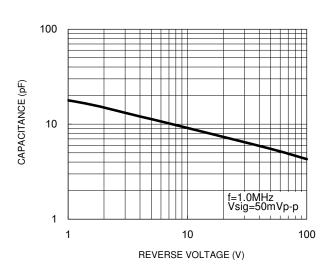
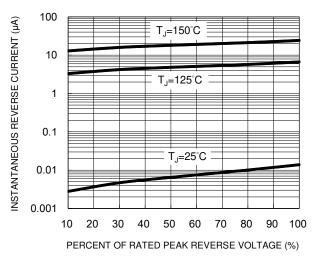


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



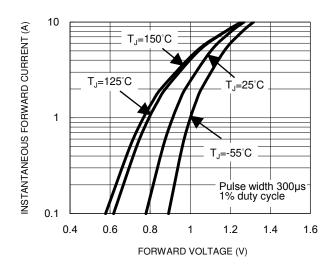
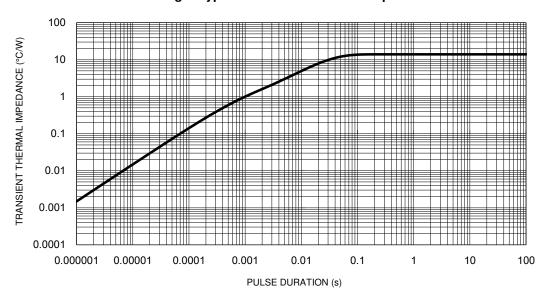


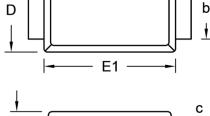
Fig.5 Typical Transient Thermal Impedance

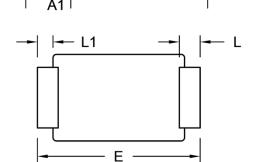




### **PACKAGE OUTLINE DIMENSIONS**

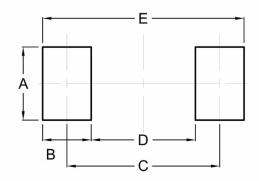
**SOD-128** 





DIM.	Unit (mm)		Unit (	inch)	
DIWI.	Min.	Max.	Min.	Max.	
Α	0.90	1.10	0.035	0.043	
A1	0.00	0.10	0.000	0.004	
b	1.60	1.90	0.063	0.075	
С	0.10	0.22	0.004	0.009	
D	2.30	2.70	0.091	0.106	
E	4.40	5.00	0.173	0.197	
E1	3.60	4.00	0.142	0.157	
L	0.40	0.80	0.016	0.031	
L1	0.30	0.60	0.012	0.024	

### **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

# **MARKING DIAGRAM**



P/N = Marking Code

YW = Date Code

F = Factory Code



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